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FOR IMMEDIATE RELEASE

Parmi Spotlights Multi-Purpose 3D AOI and High-Speed Inspection Solutions at SMTA Guadalajara 2026

San Diego, CA – September 2026 Parmi, a global leader in advanced inspection technologies for the Electronics Manufacturing Services (EMS) industry, will showcase its latest innovations at SMTA Guadalajara 2026, Booth 834. The company will feature a trio of inspection systems designed to address the industry's pressing need for enhanced process control, reduced cycle times, and the seamless integration of Industry 4.0 data analytics.

As component density increases and the adoption of conformal coating for protection expands, manufacturers face the challenge of maintaining quality without sacrificing throughput. Parmi's new solutions, including the Xceed II MP and the SigmaX 3D SPI, offer a strategic response by consolidating multiple inspection capabilities into single, high-speed platforms.

Xceed II MP: Consolidating 3D AOI, SPI and Conformal Coating Inspection

The highlight of the booth will be the **Xceed II MP**, a revolutionary multi-purpose system that performs comprehensive inspection of components, solder joints, and conformal coatings on a single machine. A key feature of Xceed is its ability for 3D AOI, 3D SPI and Conformal Coating (2D plus 3D). Historically, manufacturers have required separate, sequential inspection steps for SMD placement and coating verification, adding bottlenecks and increasing capital expenditure. Add SPI information here too



SigmaX 3D SPI: Industry-Leading Speed with Warpage Compensation

Addressing the challenges of miniaturization and PCB substrate variability, Parmi will present the **SigmaX 3D SPI**, which boasts the fastest inspection speed currently available in the industry. The system generates a real 3D image, ensuring "height" data is accurate regardless of variations in PCB color, material composition, or surface roughness. The system performs automated measurement of PCB warpage and provides automated compensation for PCB stretch and shrinkage during the printing process.

PCI-100: High-Speed Conformal Coating AOI with 2D and 3D Coating Thickness Measurement

For manufacturers requiring dedicated coating verification, Parmi will demonstrate the **PCI-100**. This system leverages a height-measuring sensor to inspect coating thickness—a critical parameter often neglected by standard 2D systems. It has 2D coverage and 3D measurement. It captures simultaneous images via UV and White LED illumination.



PCI 100

Software Integration: Deep Learning and Process Optimization

Beyond hardware, Parmi is emphasizing its software packages, designed for maximum compatibility and user convenience. The systems are underpinned by Deep Learning AI technology that reduces false calls and adapts to process variation. The suite includes:

- **AI Auto Programming**
- **AI Debugging**
- **AI OCV/OCR**
- **AI Auto Verification - auto classifies defects updates the program to remove false calls**

Additionally, **Cogiscan** will be available in the booth to discuss their flagship software featuring seamless integration tools that bring manufacturers into the future forward realm of Industry 4.0.

For more information about PARMi and its inspection solutions, visit www.parmi.com.

About PARMi

PARMi is a manufacturer specializing in 3D inspection equipment used to improve print quality and yield in SMT production lines. Throughout its 28 year history, the company has specialized in developing in-house expertise in laser measurement and software support. PARMi is a global leader in Electronics product inspection in 3D. For more information, visit www.parmi.com.

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